Preferred Device

Triacs

Silicon Bidirectional Thyristors

Designed primarily for full-wave ac control applications, such as light dimmers, motor controls, heating controls and power supplies; or wherever full-wave silicon gate controlled solid-state devices are needed. Triac type thyristors switch from a blocking to a conducting state for either polarity of applied main terminal voltage with positive or negative gate triggering.

- Blocking Voltage to 800 Volts
- All Diffused and Glass Passivated Junctions for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Gate Triggering Guaranteed in all Four Quadrants
- For 400 Hz Operation, Consult Factory
- Device Marking: Logo, Device Type, e.g., 2N6344, Date Code

MAXIMUM RATINGS (T_{.J} = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
*Peak Repetitive Off–State Voltage(1) (T _J = -40 to +110°C, Sine Wave 50 to 60 Hz, Gate Open) 2N6344 2N6349	V _{DRM} , V _{RRM}	600 800	Volts
*On-State RMS Current (T _C = +80°C) Full Cycle Sine Wave 50 to 60 Hz (T _C = +90°C)	IT(RMS)	8.0 4.0	Amps
*Peak Non-Repetitive Surge Current (One Full Cycle, Sine Wave 60 Hz, T _C = +25°C) Preceded and followed by rated current	ITSM	100	Amps
Circuit Fusing Consideration (t = 8.3 ms)	I ² t	40	A ² s
*Peak Gate Power (T _C = +80°C, Pulse Width = 2 μs)	PGM	20	Watts
*Average Gate Power (T _C = +80°C, t = 8.3 ms)	PG(AV)	0.5	Watt
*Peak Gate Current (T _C = +80°C, Pulse Width = 2.0 μs)	IGM	2.0	Amps
*Peak Gate Voltage (T _C = +80°C, Pulse Width = 2.0 μs)	VGМ	10	Volts
*Operating Junction Temperature Range	TJ	-40 to +125	°C
*Storage Temperature Range	T _{stg}	-40 to +150	°C

⁽¹⁾ V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

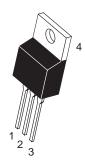


ON Semiconductor

http://onsemi.com

TRIACS 8 AMPERES RMS 600 thru 800 VOLTS





TO-220AB CASE 221A STYLE 4

PIN ASSIGNMENT				
1	Main Terminal 1			
2	Main Terminal 2			
3	Gate			
4	Main Terminal 2			

ORDERING INFORMATION

Device	Package	Shipping
2N6344	TO220AB	500/Box
2N6349	TO220AB	500/Box

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
*Thermal Resistance, Junction to Case	$R_{ heta JC}$	2.2	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

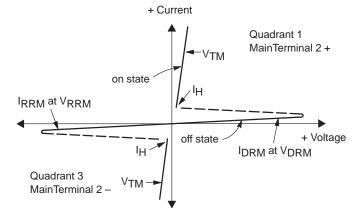
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic	Symbol	Min	Тур	Max	Unit
FF CHARACTERISTICS	•		•	•	•
*Peak Repetitive Blocking Current $(V_D = Rated \ V_{DRM}, \ V_{RRM}; \ Gate \ Open)$ $T_J = 25^{\circ}C$ $T_J = 100^{\circ}C$	I _{DRM} , IRRM		_	10 2.0	μA mA
ON CHARACTERISTICS	•	•		•	
*Peak On–State Voltage (I _{TM} = ±11 A Peak; Pulse Width = 1 to 2 ms, Duty Cycle ≤2%)	VTM	-	1.3	1.55	Volts
Gate Trigger Current (Continuous dc) $ (V_D = 12 \text{ Vdc, R}_L = 100 \text{ Ohms}) $ $ \text{MT2(+), G(+)} $ $ \text{MT2(+), G(-)} $ $ \text{MT2(-), G(-)} $ $ \text{MT2(-), G(+)} $ $ ^*\text{MT2(+), G(+); MT2(-), G(-) T_C = -40^{\circ}\text{C}} $ $ ^*\text{MT2(+), G(-); MT2(-), G(+) T_C = -40^{\circ}\text{C}} $	^I GT		12 12 20 35 —	50 75 50 75 100 125	mA
Gate Trigger Voltage (Continuous dc) $ (V_D = 12 \text{ Vdc, R}_L = 100 \text{ Ohms}) $ $ MT2(+), G(+) $ $ MT2(+), G(-) $ $ MT2(-), G(-) $ $ MT2(-), G(+) $ $ ^*MT2(+), G(+); MT2(-), G(-) T_C = -40^{\circ}C $ $ ^*MT2(+), G(-); MT2(-), G(+) T_C = -40^{\circ}C $	V _{GT}	_ _ _ _ _	0.9 0.9 1.1 1.4 —	2.0 2.5 2.0 2.5 2.5 3.0	Volts
Gate Non–Trigger Voltage (Continuous dc) (V _D = Rated V _{DRM} , R _L = 10 k Ohms, T _J = 100°C) *MT2(+), G(+); MT2(-), G(-); MT2(+), G(-); MT2(-), G(-)	V _{GD}	0.2	_	_	Volts
*Holding Current ($V_D = 12$ Vdc, Gate Open) $T_C = 25$ °C (Initiating Current = ± 200 mA) $*T_C = -40$ °C	lн	_	6.0 —	40 75	mA
*Turn-On Time (V_D = Rated V_{DRM} , I_{TM} = 11 A, I_{GT} = 120 mA, Rise Time = 0.1 μ s, Pulse Width = 2 μ s)	tgt	_	1.5	2.0	μs
DYNAMIC CHARACTERISTICS		-	•	•	•
Critical Rate of Rise of Commutation Voltage $(V_D = Rated\ V_{DRM},\ I_{TM} = 11\ A,\ Commutating\ di/dt = 4.0\ A/ms,\ Gate\ Unenergized,\ T_C = 80^{\circ}C)$	dv/dt(c)	_	5.0	_	V/µs

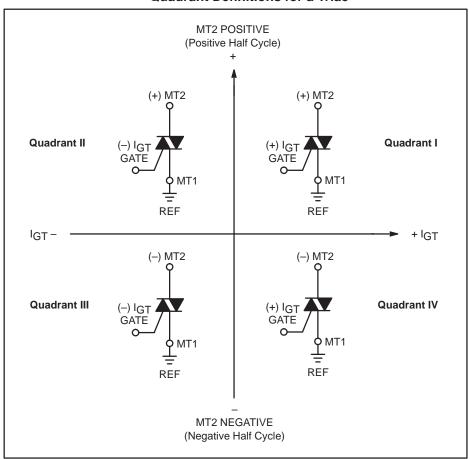
^{*}Indicates JEDEC Registered Data.

Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
VDRM	Peak Repetitive Forward Off State Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Reverse Off State Voltage
IRRM	Peak Reverse Blocking Current
V _{TM}	Maximum On State Voltage
lΗ	Holding Current



Quadrant Definitions for a Triac



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.

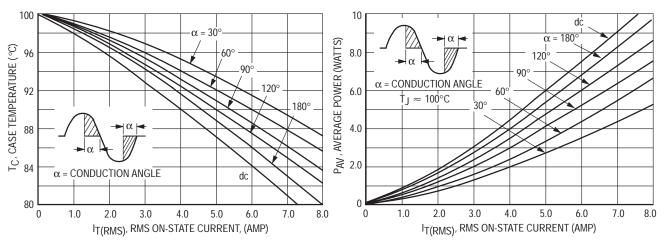


Figure 1. RMS Current Derating

Figure 2. On-State Power Dissipation

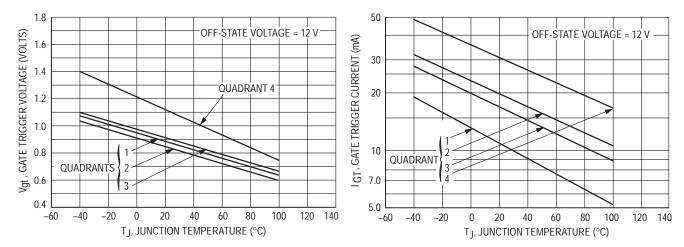


Figure 3. Typical Gate Trigger Voltage

Figure 4. Typical Gate Trigger Current

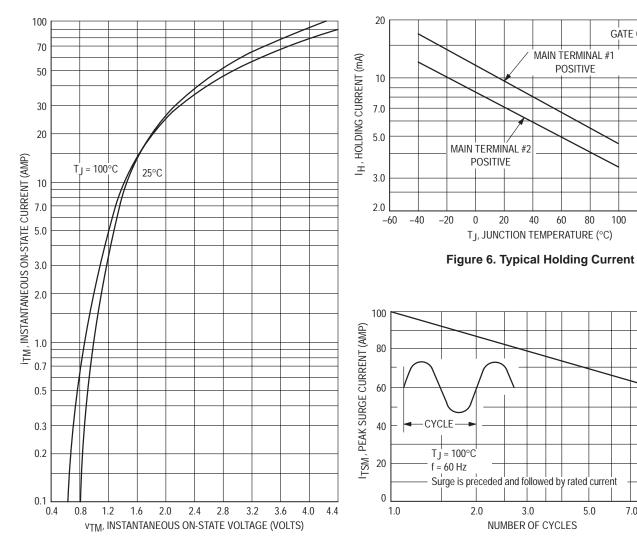


Figure 5. On-State Characteristics

Figure 7. Maximum Non-Repetitive **Surge Current**

3.0

GATE OPEN

MAIN TERMINAL #1

POSITIVE

40

60

80

100

7.0

5.0

10

120 140

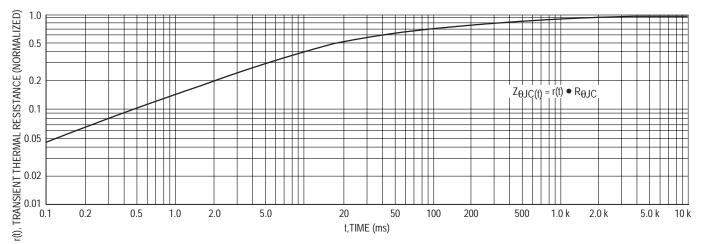
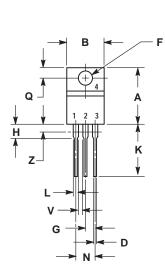
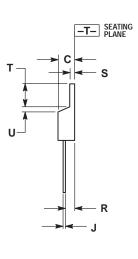


Figure 8. Typical Thermal Response

PACKAGE DIMENSIONS

TO-220AB CASE 221A-07 ISSUE Z





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

- STYLE 4:
 PIN 1. MAIN TERMINAL 1
 2. MAIN TERMINAL 2
 3. GATE
 4. MAIN TERMINAL 2

Notes

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